

#### AMPMODU | AMPMODU Headers

TE Internal #: 102203-4

PCB Mount Header, Right Angle, Board-to-Board, 7 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder,

AMPMODU Headers

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PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Right Angle
Connector System: Board-to-Board

Number of Positions: 7
Number of Rows: 1

#### **Features**

#### **Product Type Features**

| PCB Connector Assembly Type       | PCB Mount Header      |
|-----------------------------------|-----------------------|
| Connector System                  | Board-to-Board        |
| Header Type                       | Fully Shrouded        |
| Connector & Contact Terminates To | Printed Circuit Board |

#### **Configuration Features**

| Connector Contact Load Condition | Fully Loaded |
|----------------------------------|--------------|
| PCB Mount Orientation            | Right Angle  |
| Number of Positions              | 7            |
| Number of Rows                   | 1            |

#### **Electrical Characteristics**

| Insulation Resistance                 | 5000 MΩ  |
|---------------------------------------|----------|
| Dielectric Withstanding Voltage (Max) | 750 Vrms |

#### **Body Features**

| Connector Profile     | Standard |
|-----------------------|----------|
| Primary Product Color | Black    |

### **Contact Features**

| Mating Square Post Dimension                            | .64 mm[.025 in]               |
|---|-------------------------------|
| PCB Contact Termination Area Plating Material Thickness | 2.54 – 5.08 μm[100 – 200 μin] |



| PCB Contact Termination Area Plating Material Finish | Matte                      |
|--|----------------------------|
| Contact Shape & Form                                 | Square                     |
| Contact Underplating Material                        | Nickel                     |
| PCB Contact Termination Area Plating Material        | Tin-Lead                   |
| Contact Base Material                                | Phosphor Bronze            |
| Contact Mating Area Plating Material                 | Gold                       |
| Contact Mating Area Plating Material Thickness       | .381 μm[15 μin]            |
| Contact Type   | Pin                        |
| Contact Current Rating (Max)                         | 3 A                        |
| Termination Features                                 |                            |
| Square Termination Post & Tail Dimension             | .64 mm[.025 in]            |
| Termination Post & Tail Length                       | 2.79 mm[.11 in]            |
| Termination Method to Printed Circuit Board          | Through Hole - Solder      |
| Mechanical Attachment                                |                            |
| Mating Alignment                                     | With                       |
| Mating Alignment Type                                | Polarization               |
| PCB Mount Retention                                  | Without                    |
| PCB Mount Alignment                                  | Without                    |
| Connector Mounting Type                              | Board Mount                |
| Housing Features                                     |                            |
| Centerline (Pitch)                                   | 2.54 mm[.1 in]             |
| Housing Material                                     | Thermoplastic              |
| Dimensions   |                            |
| Row-to-Row Spacing                                   | 2.54 mm[.1 in]             |
| PCB Thickness (Recommended)                          | 1.4 mm[.055 in]            |
| Usage Conditions                                     |                            |
| Housing Temperature Rating                           | Standard                   |
| Operating Temperature Range                          | -65 – 105 °C[-85 – 221 °F] |
| Operation/Application                                |                            |
| Solder Process Feature                               | Board Standoff             |
| Circuit Application                                  | Signal                     |
| Industry Standards                                   |                            |



| Agency/Standard                        | CSA                   |
|--|-----------------------|
| Approved Standards                     | CSA LR7189, UL E28476 |
| UL Flammability Rating                 | UL 94V-0              |
|  |                       |
| Packaging Features                     |                       |
| Packaging Features  Packaging Quantity | 25                    |

## **Product Compliance**

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU                  | Not Compliant  |
|---|--|
| EU ELV Directive 2000/53/EC                   | Not Compliant  |
| China RoHS 2 Directive MIIT Order No 32, 2016 | Restricted Materials Above Threshold   |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2022 (223) SVHC > Threshold: Pb (40% in Component Part) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location. |
| Halogen Content                               | BFR/CFR/PVC Free, but Br/Cl >900 ppm in other sources.   |
| Solder Process Capability                     | Wave solder capable to 240°C   |

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# Compatible Parts







# Also in the Series | AMPMODU Headers



PCB Connector Mounting(1)



PCB Connector Shrouds(1)



PCB Headers & Receptacles(4872)



PCB Latches, Locks & Retainers(1)



Wire-to-Board Connector Assemblies & Housings(5)



Wire-to-Board Connector Contacts(65)

# Customers Also Bought





REC, 2P, GRY, N













#### **Documents**

#### **Product Drawings**

07 MODII HDR SRRA SHRD .100CL

English

**CAD Files** 

3D PDF

English

**Customer View Model** 

ENG\_CVM\_102203-4\_V.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_102203-4\_V.3d\_stp.zip

English

**Customer View Model** 

ENG\_CVM\_102203-4\_V.2d\_dxf.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

#### Datasheets & Catalog Pages

**AMPMODU Interconnetion System** 

**AMPMODU Interconnetion System** 

English

## Product Environmental Compliance

TE Material Declaration

English